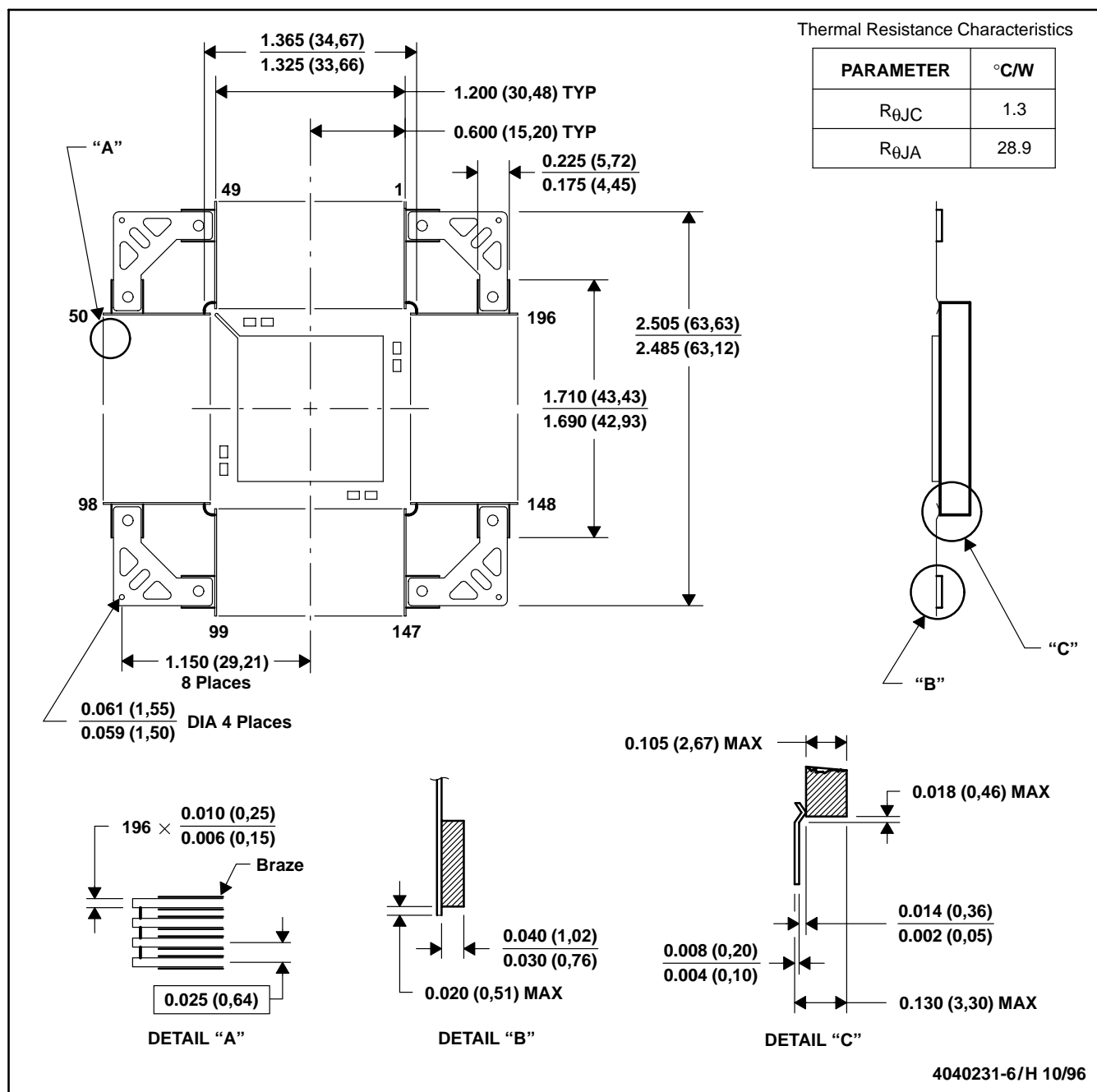


HFG (S-CQFP-F196)

CERAMIC QUAD FLATPACK WITH TIE BAR



4040231-6/H 10/96

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Ceramic quad flatpack with flat leads brazed to nonconductive tie-bar carrier
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MO-113 AB

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